

MICRON TECHNOLOGY INC  
Form 8-K/A  
October 02, 2013

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UNITED STATES  
SECURITIES AND EXCHANGE COMMISSION  
Washington, D.C. 20549

FORM 8-K/A

CURRENT REPORT

Pursuant to Section 13 OR 15(d) of The Securities Exchange Act of 1934

July 31, 2013

Date of Report (date of earliest event reported)

MICRON TECHNOLOGY, INC.  
(Exact name of registrant as specified in its charter)

|   |  |   |
|---|--|---|
| Delaware<br>(State or other jurisdiction of<br>incorporation) | 1-10658<br>(Commission File<br>Number) | 75-1618004<br>(I.R.S. Employer<br>Identification No.) |
|---|--|---|

8000 South Federal Way  
Boise, Idaho 83716-9632  
(Address of principal executive  
offices)

(208) 368-4000  
(Registrant's telephone number, including  
area code)

Check the appropriate box below if the Form 8-K filing is intended to simultaneously satisfy the filing obligation of the registrant under any of the following provisions (see General Instruction A.2. below):

- Written communications pursuant to Rule 425 under the Securities Act (17 CFR 230.425)
- Soliciting material pursuant to Rule 14a-12 under the Exchange Act (17 CFR 240.14a-12)
- Pre-commencement communications pursuant to Rule 14d-2(b) under the Exchange Act (17 CFR 240.14d-2(b))
- Pre-commencement communications pursuant to Rule 13e-4(c) under the Exchange Act (17 CFR 240.13e-4c)



Item 1.01 Entry into a Material Agreement

On August 6, 2013, Micron Technology, Inc. (“Micron”) filed a Current Report on Form 8-K (the “8-K”) pursuant to Item 1.01 related to the entry into various agreements regarding Micron’s acquisition of Elpida Memory, Inc. (“Elpida”). Micron filed a Confidential Treatment Request with the Securities and Exchange Commission (“SEC”) related to these agreements and redacted portions of the agreements that were filed as exhibits to the 8-K.

This Amendment to the 8-K is being filed solely for the purpose of refiling Exhibits 10.139 and 10.141, which were initially filed with the 8-K on August 6, 2013. Certain redactions to Exhibits 10.139 and 10.141 have been revised in response to a comment letter received by Micron from the SEC.

Item 9.01 Financial Statements and Exhibits

Exhibit

| Exhibit No. | Description  |
|-------------|--|
| 10.139*     | English Translation of Front-End Manufacturing Supply Agreement, dated July 31, 2013, by and between Micron Semiconductor Asia Pte. Ltd. and Elpida Memory, Inc. |
| 10.141*     | English Translation of General Services Agreement, dated July 31, 2013, by and between Micron Semiconductor Asia Pte. Ltd. and Elpida Memory, Inc.               |

\*Certain portions have been omitted pursuant to a confidential treatment request. Omitted information has been filed separately with the Securities and Exchange Commission.

SIGNATURE

Pursuant to the requirements of the Securities Exchange Act of 1934, the Registrant has duly caused this report to be signed on its behalf by the undersigned hereunto duly authorized.

MICRON TECHNOLOGY, INC.

Date: October 2, 2013

By: /s/ Ronald C. Foster  
Name: Ronald C. Foster  
Title: Chief Financial Officer and  
Vice President of Finance

INDEX TO EXHIBITS

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